



DESCRIPTION

The IS124 consists of an infrared light emitting diode optically coupled to an NPN silicon photo transistor in a space efficient Mini Flat Package.

FEATURES

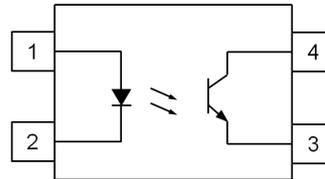
- Low Profile Package
- AC Isolation Voltage 3750V_{RMS}
- CTR Typical 100% at I_F 0.5mA V_{CE} 1.5V
- Wide Operating Temperature Range -55°C to +110°C
- Lead Free and RoHS Compliant
- UL File E91231 model "FPT2"

APPLICATIONS

- Computer Terminals
- Industrial System Controllers
- Measuring Instruments
- Signal Transmission between Systems of Different Potentials and Impedance

ORDER INFORMATION

- Available in Tape and Reel with 3000 pieces per reel



- 1 Anode
- 2 Cathode
- 3 Emitter
- 4 Collector

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

Forward Current	50mA
Peak Forward Current (100µs, 100Hz)	1A
Reverse Voltage	6V
Power Dissipation	70mW
Junction Temperature	125°C

Output

Collector to Emitter Voltage V _{CEO}	80V
Emitter to Collector Voltage V _{ECO}	6V
Collector Current	50mA
Power Dissipation	150mW
Junction Temperature	125°C

Total Package

Isolation Voltage	3750V _{RMS}
Total Power Dissipation	170mW
Operating Temperature	-55 to +110°C
Storage Temperature	-55 to +150°C
Lead Soldering Temperature (10s)	260°C

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward Voltage	V_F	$I_F = 20\text{mA}$		1.2	1.4	V
Reverse Current	I_R	$V_R = 4\text{V}$			10	μA
Terminal Capacitance	C_t	$V = 0\text{V}, f = 1\text{KHz}$		30	250	pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Collector-Emitter Breakdown Voltage	BV_{CEO}	$I_C = 0.1\text{mA}, I_F = 0\text{mA}$	80			V
Emitter-Collector Breakdown Voltage	BV_{ECO}	$I_E = 10\mu\text{A}, I_F = 0\text{mA}$	6			V
Collector-Emitter Dark Current	I_{CEO}	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$			100	nA

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Current Transfer Ratio	CTR	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$	50		600	%
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F = 20\text{mA}, I_C = 1\text{mA}$			0.2	V
Floating Capacitance	C_f	$V = 0\text{V}, f = 1\text{MHz}$		0.6	1	pF
Output Rise Time	t_r	$V_{CE} = 2\text{V}$ $I_C = 2\text{mA}$ $R_L = 100\Omega$		4	18	μs
Output Fall Time	t_f			3	18	μs

ISOLATION

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Isolation Voltage	V_{ISO}	$RH = 40\% \text{ to } 60\%, t = 1 \text{ min}$	3750			V_{RMS}
Input - Output Resistance	R_{I-O}	$RH = 40\% \text{ to } 60\%$ $V_{I-O} = 500\text{VDC}$	5×10^{10}	1×10^{11}		Ω

Measured with input leads shorted together and output leads shorted together.



IS124

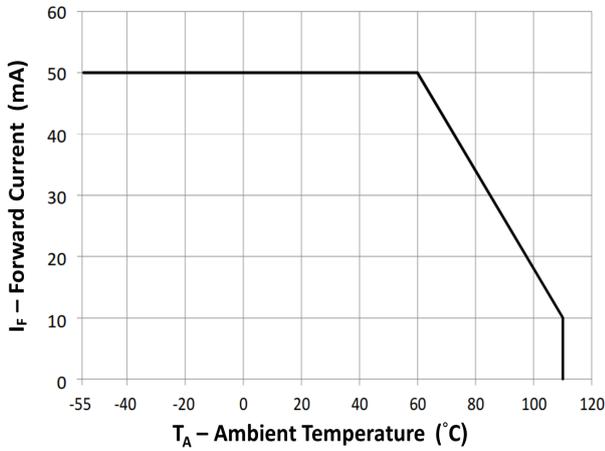


Fig 1 Forward Current vs Ambient Temperature

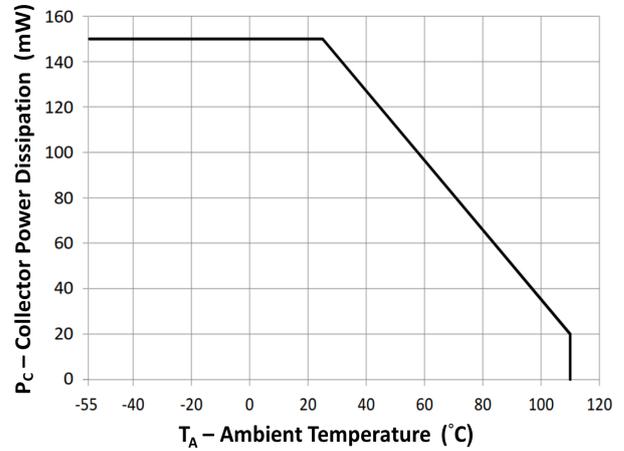


Fig 2 Collector Power Dissipation vs Ambient Temperature

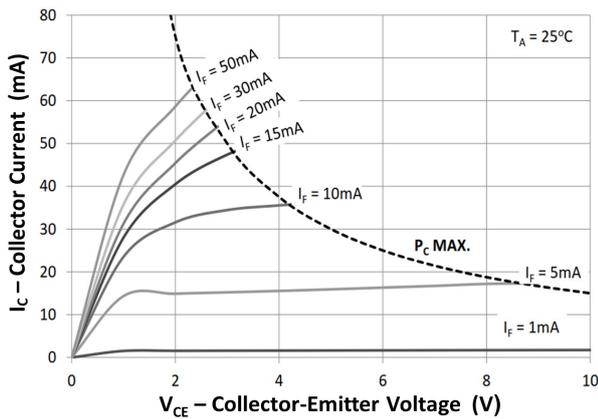


Fig 3 Collector Current vs Collector-Emitter Voltage

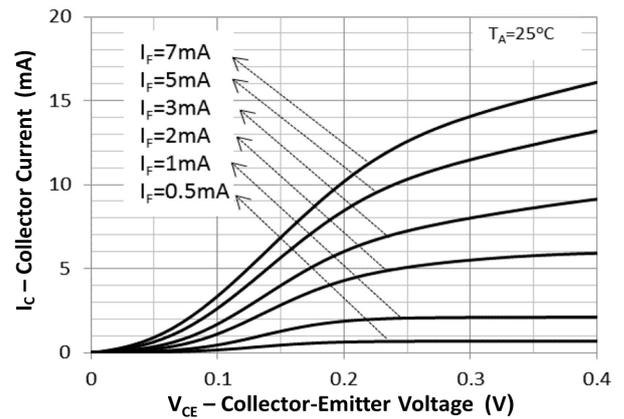


Fig 4 Collector Current vs Collector-Emitter Saturation Voltage

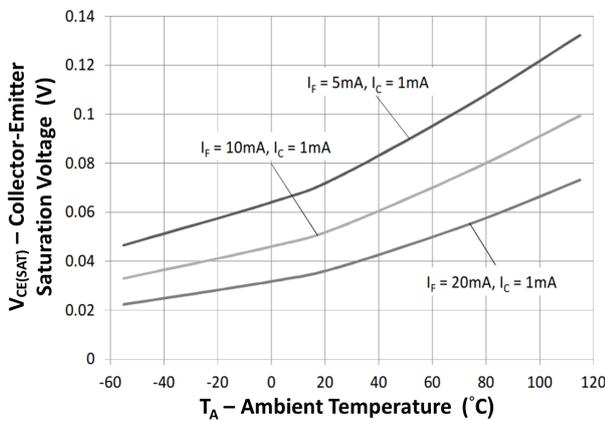


Fig 5 Collector-Emitter Saturation Voltage vs Ambient Temperature

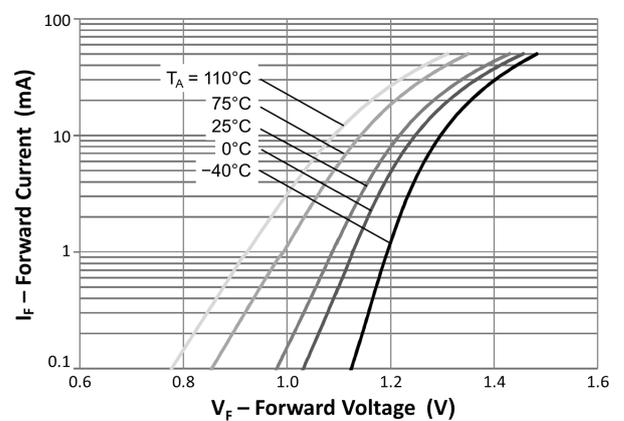


Fig 6 Forward Current vs Forward Voltage

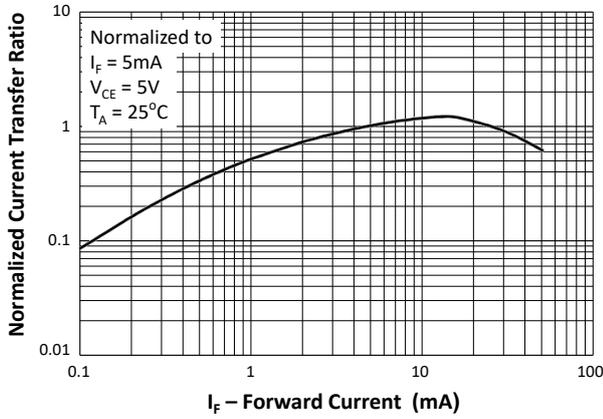


Fig 7 Normalized Current Transfer Ratio vs Forward Current

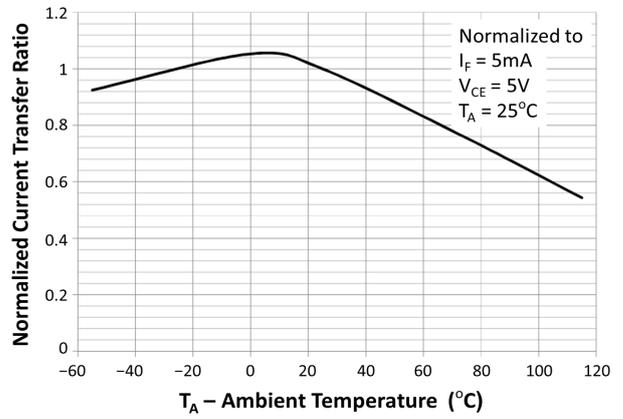


Fig 8 Normalized Current Transfer Ratio vs Ambient Temperature

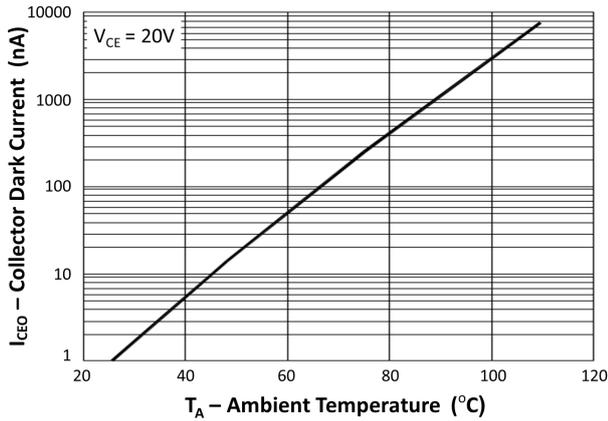


Fig 9 Collector Dark Current vs Ambient Temperature

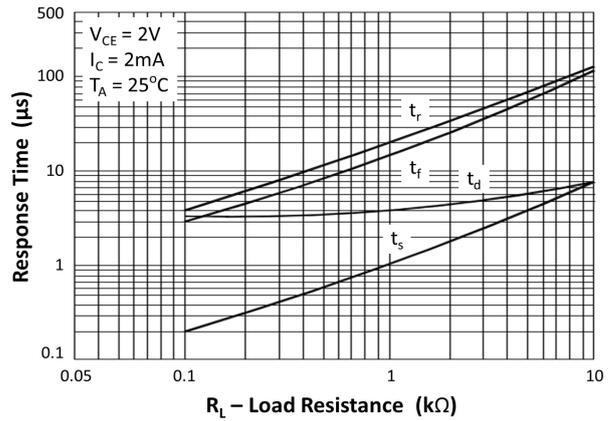


Fig 10 Response Time vs Load Resistance

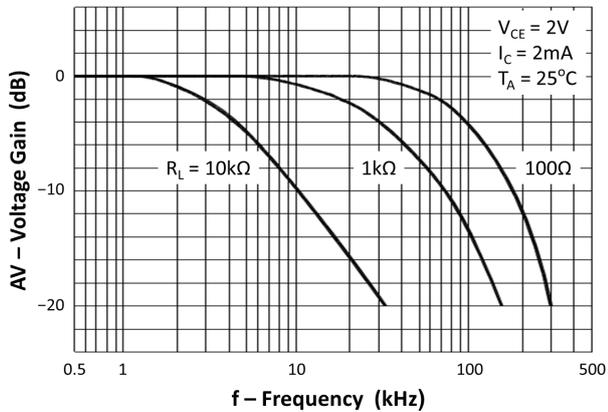
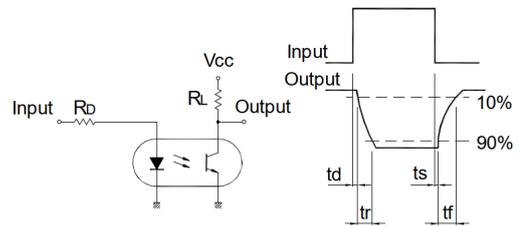
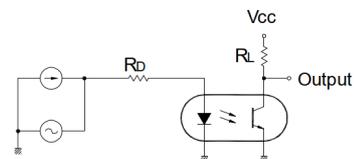


Fig 11 Frequency Response



Response Time Test Circuit



Frequency Response Test Circuit

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ORDER INFORMATION

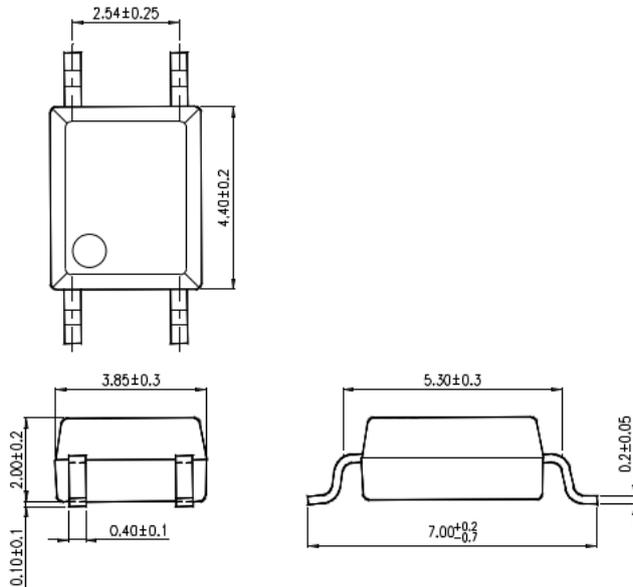
IS124			
After PN	PN	Description	Packing quantity
None	IS124	Surface Mount Tape & Reel	3000 pcs per reel

DEVICE MARKING

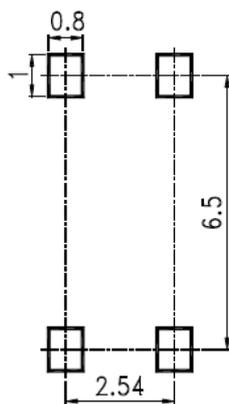


FPT2 denotes Device Part Number
/ denotes Isocom
Y denotes 1 digit Year code
WW denotes 2 digit Week code

PACKAGE DIMENSIONS (mm)



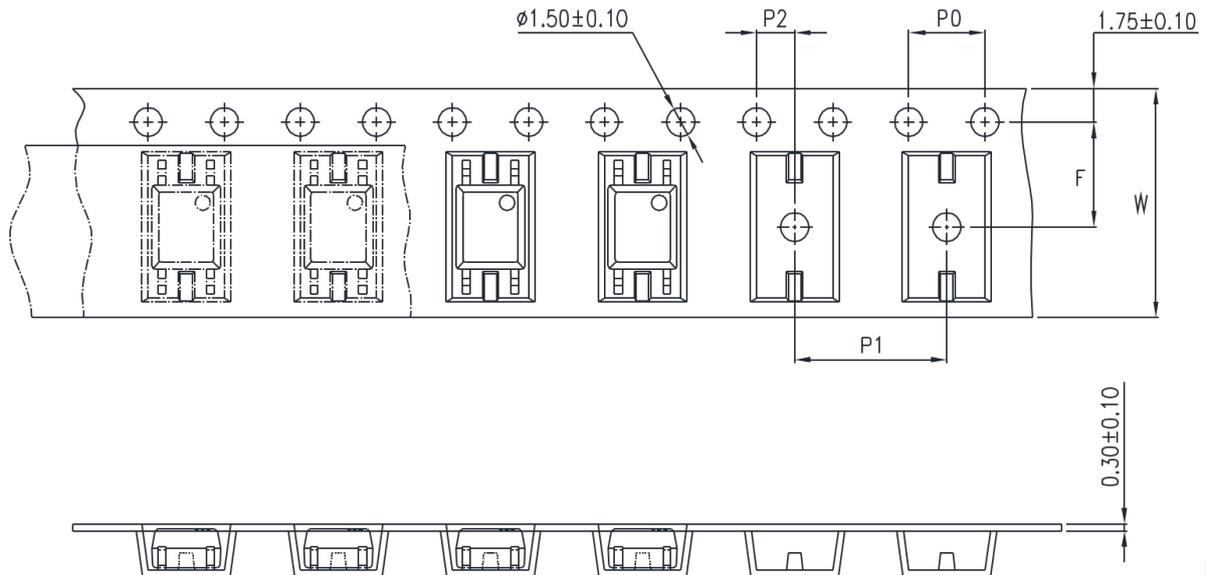
RECOMMENDED SOLDER PAD LAYOUT (mm)





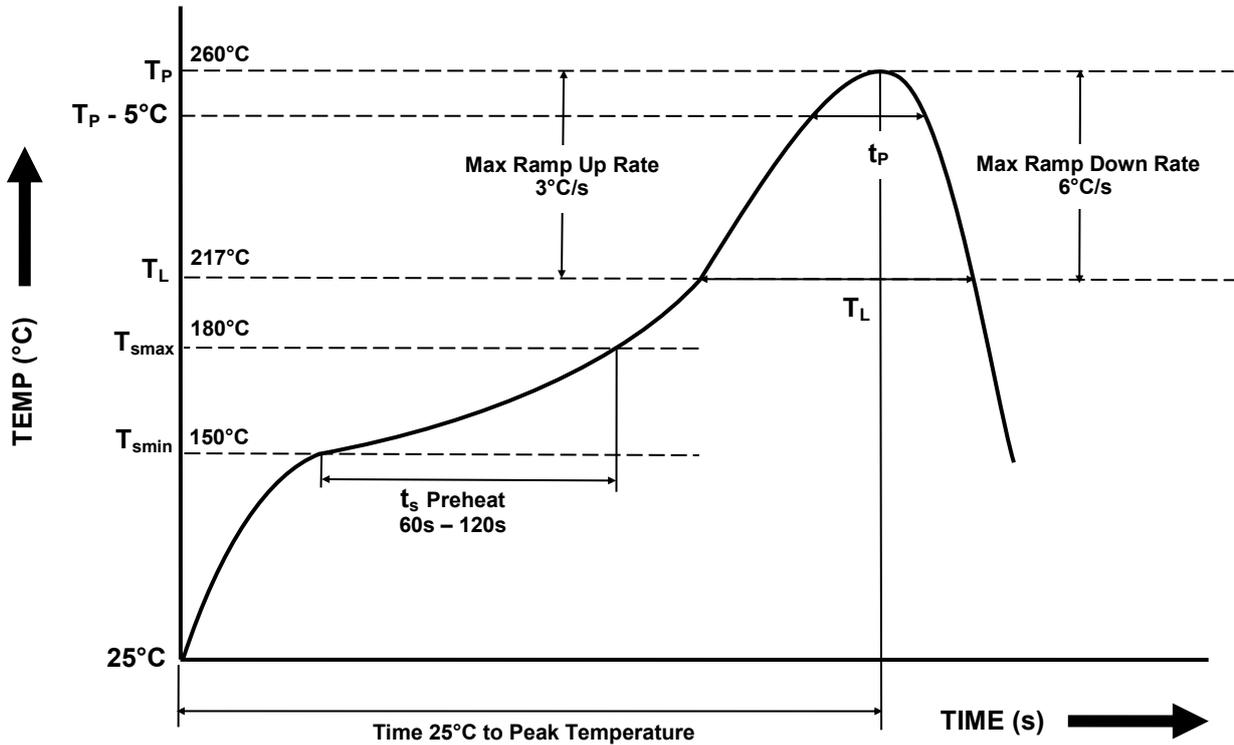
IS124

TAPE AND REEL PACKAGING



Description	Symbol	Dimension mm (inch)
Tape Width	W	12 ± 0.3 (0.47)
Pitch of Sprocket Holes	P_0	4 ± 0.1 (0.15)
Distance of Compartment to Sprocket Holes	F	5.5 ± 0.1 (0.217)
	P_2	2 ± 0.1 (0.079)
Distance of Compartment to Compartment	P_1	8 ± 0.1 (0.315)

IR REFLOW SOLDERING TEMPERATURE PROFILE
One Time Reflow Soldering is Recommended.
Do not immerse device body in solder paste.



Profile Details	Conditions
Preheat - Min Temperature (T _{SMIN}) - Max Temperature (T _{SMAX}) - Time T _{SMIN} to T _{SMAX} (t _s)	150°C 180°C 60s - 120s
Soldering Zone - Peak Temperature (T _P) - Liquidous Temperature (T _L) - Time within 5°C of Actual Peak Temperature (T _P - 5°C) - Time maintained above T _L (t _L) - Ramp Up Rate (T _L to T _P) - Ramp Down Rate (T _P to T _L)	260°C 217°C 20s 60s 3°C/s max 3 - 6°C/s
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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